

07-09-2001

FLH Ref. No.: 450100-03124



101769694

EET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies) **7-301**
 Koji ASHIZAKI, Yushi IHARA, Takahiro NISHIKAWA, Yuji KAWAMURA, Kohei NOJIRI, Tsuyoshi IDE, Toshiya IZUMI, Kensuke BABA
 Additional name(s) of conveying party(ies) attached?
 Yes No

2. Name and address of receiving party(ies)
 Name: SONY CORPORATION
 7-35 Kitashinagawa 6-chome
 Shinagawa-Ku, Tokyo 141-0001, Japan
 Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:
 Assignment
 Security Agreement
 Merger
 Change of Name
 Other
 Execution Date(s): June 1, June 6, June 7, June 7, June 1, June 1, June 11 and June 6, 2001

JUL - 3 2001

4. Application number(s) or patent number(s):
 If this document is being filed together with a new application, the execution date of the application is:
 A. Patent Application No.(s) 09/826,188 filed April 4, 2001
 Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
 Name: WILLIAM S. FROMMER
 Internal Address: FROMMER LAWRENCE & HAUG LLP
 Street Address: 745 FIFTH AVENUE
 City: NEW YORK State: N.Y. Zip: 10151

6. Total number of applications and patents involved 1
 7. Total fee (37 CFR 3.41) \$ 40.00
 Enclosed
 Authorized to be charged to deposit account 50-0320
 8. Deposit account number:
 (Attach duplicate copy of this page if paying by deposit account)

Do not use this space

9. Statement and signature.
 To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

BRUNO POLITO
 Name of Person Signing

Signature

June 29, 2001
 Date

Total number of pages including cover sheet, attachments, and document: 3

Do not detach this portion

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
 Box Assignments
 Washington, D.C. 20231

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

201009200810

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

DATA CONVERTING APPARATUS AND METHOD, PRINTING APPARATUS AND METHOD, PRINTING CONTROLLING APPARATUS AND METHOD, PRINTING SYSTEM AND METHOD, AND DATA TRANSMITTING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/826,188, Filing Date: April 4, 2001.

This assignment executed on the dates indicated below.

Koji ASHIZAKI

Name of first or sole inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of first or sole inventor

Signature of first or sole inventor

Date of this assignment

June 1, 2001

Yushi IHARA

Name of second inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of second inventor

Signature of second inventor

Date of this assignment

June 6, 2001

Takahiro NISHIKAWA

Name of third inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Signature of third inventor

Date of this assignment

June 7, 2001

ADDITIONAL INVENTORS

Yuji KAWAMURA

Name of fourth inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Signature of fourth inventor

Yuji Kawamura

Date of this assignment

June 7, 2001

Kohei NOJIRI

Name of fifth inventor

Execution date of U.S. Patent Application

Saitama, Japan

Residence of fifth inventor

Signature of fifth inventor

Kohei Nojiri

Date of this assignment

June 1, 2001

Tsuyoshi IDE

Name of sixth inventor

Execution date of U.S. Patent Application

Chiba, Japan

Residence of sixth inventor

Signature of sixth inventor

Tsuyoshi Ide

Date of this assignment

June 1, 2001

Toshiya IZUMI

Name of seventh inventor

Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

Signature of seventh inventor

Toshiya Izumi

Date of this assignment

June 11, 2001

Kensuke BABA

Name of eighth inventor

Execution date of U.S. Patent Application

Tokyo, Japan

Residence of eighth inventor

Signature of eighth inventor

Kensuke Baba

Date of this assignment

June 6, 2001